TECHNO-ADHESIVE HTM

Technical specification

Application temperature	°C	800
Short term stress	°C	1000
Density	kg/m^3	2300
Consistency		powder
Viscosity	cps	1100
Linear heat dilatation		4.7 x 10^{-6}
Compressional strength	N/cm^2	2700
Bending strength	N/cm^2	320
Specific electrical resistance	O/cm	10^8
Water take-up	%	max. 1
Storage		frost free
Delivery form (dose) Other delivery forms on inquiry	g	100, 250, 1000
Colour		white

The **TECHNO-ADHESIVE HTM** is a product with large thermal expansion for bonding metals for utilisation at high temperatures. The bonded joint is resistant to oxidising as well as to reducing atmospheres.

Typical application fields:
» Bonding of metals

(1) We are able to supply special formats and special thicknesses on request. We will be pleased to manufacture stampings, milled parts or cuttings according to your drawings.
(2) The classification temperature is not to be equated with the maximum application temperature, in particular when physical conditions such as tensile or pressure loads are involved. For applications as high-temperature insulation, lower temperatures must always be applied. In these cases, our Engineering department will offer assistance and support.
(3) Heat transmission calculations for this material can be requested from our Engineering department.

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